

COPY**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Jau-Yuen SU

Serial No.: 09/394,918

Filed: September 13, 1999

For: PROCESS FOR SAWING SUBSTRATE STRIP

Examiner: O. Flores-Sanchez

Atty. Dkt.: SUJA3001/REF/WKP

AMENDMENT AND RESPONSECommissioner for Patents
Washington, D.C. 20231

Sir:

This is responsive to the Office Action mailed October 25, 2001 (Paper No. 12) in the above application. Reconsideration of the application is respectfully requested in view of the following amendments and remarks.

AMENDMENT

Please amend this application as follows:

IN THE CLAIMS

Please amend claim 9 as follows (an APPENDIX OF MARKED-UP AMENDED CLAIM is attached):

21 -9. (Twice Amended) The process as claimed in Claim 7, further comprising the step of cutting the substrate strip according to cutting tracks defined by the cutting marks parallel to the longitudinal axis.